

L Number	Hits	Search Text	DB	Time stamp
3	2	(wire adj bonder adj stud adj (ball or bump))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/29 16:56
4	368	(wire adj bonder) with (stud or ball or bump)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/29 17:11
5	194	((wire adj bonder) with (stud or ball or bump)) and pad	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/29 17:13